TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN Number:	**20261030001.1**	**PCN Issued**	November 02, 2026
Qualification of RFAB as an additional Wafer Fab site for select devices		**Sample request deadline:**	January 01, 2027
		Estimated 1st ship date:	January 31, 2027
***Sample requests received after** January 01, 2027* **will not be supported.**			

Change type(s)
Packing/Shipping/Labeling Wafer Fab Site Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab site for the products listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process Technology**	**Wafer Diameter**	**Additional Fab site**	**Process Technology**	**Wafer Diameter**
FFAB	LBC7	200mm	**RFAB**	LBC7	**300mm**

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	• Request the Supporting Data Packet for more details on the changes.
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	**RFB**	**USA**	**Richardson**

Sample product shipping label (not actual product label):



Products Affected

TCA9534PWR.B	TCA9534ADWR	TCA9554DWR	TCA9535MRGER
TCA9535RGER	TCA9535PWR	TCA9534DWT	TCA9538PWR
TCA9534DWR	PCA9534PWRG4	TCA9538DBR	TCA9554ADBR
PCA9534RGVR	PCA9534APWR	TCA9535RTWR	PCA9539RGER
TCA9554DBR	TCA9554APWR	TCA9554DWT	TCA9534ADWT
TCA9509MRVHR	PCA9555PWRG4	TCA9509DGKR	TCA9554PWR
PCA9535PWR	TCA9554ADWR	PCA9555PWR	PCA9539PWR
PCA9554PWR	SN65HVD64RGTR	PCA9534ARGTR	PCA9539PWRG4
TCA9534PWR	PCA9555DBR	TCA9554DBQR	PCA9554ARGTR
PCA9534ARGTRG4	TCA9534APWR	TCA9554ADBQR	PCA9555RGERG4
TCA9509RVHR	PCA9555RGER	TCA9535DBR	PCA9534PWR
TCA9554ADWT	PCA9535RGER	TCA9535DBT	

Qualification Report

INT-TXP Commercial LBC7 FFAB to RFAB Offload
Approve Date 13-October -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: PCA9555PWR	Qual Device: SN65HVD64RGTR	Qual Device: TCA9509DGKR	Qual Device: TCA9554APWR	QBS Process Reference: SN657095YFFR	QBS Product Reference: TCA9539QPWRQ1
HTOL	B1	Life Test	140C	480 Hours	-	-	-	-	3/231/0	-
ELFR	B2	ELFR	125C	48 Hours	-	-	-	-	3/3000/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	1/3/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/30/0	1/30/0	-	1/30/0
FTY	E6	Final Test Yield	-	-	1/All/0	1/All/0	1/All/0	1/All/0	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device PCA9555PWR is qualified at MSL1 260C
- Qual Device SN65HVD64RGTR is qualified at MSL2 260C
- Qual Device TCA9509DGKR is qualified at MSL1 260C
- Qual Device TCA9554APWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2604-081

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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